



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Teck Kheng Lee

**Serial No.:** 10/782,270

**Filed:** February 18, 2004

**For:** INTERPOSER SUBSTRATE AND  
WAFER SCALE INTERPOSER  
SUBSTRATE MEMBER FOR USE WITH  
FLIP-CHIP CONFIGURED  
SEMICONDUCTOR DICE

**Confirmation No.:** 4215

**Examiner:** J. Clark

**Group Art Unit:** 2815

**Attorney Docket No.:** 2269-4973.1US  
(00-0593.01/US)

**Notice of Allowance Mailed:**

January 26, 2006

**NOTICE OF EXPRESS MAILING**

Express Mail Mailing Label Number: EL995987189US

Date of Deposit with USPS: April 26, 2006

Person making Deposit: Timothy Palfreyman

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Serial No. 10/782,270**

**Amendments to the Specification** begin on page 3 of this paper;

**Amendments to the Claims** are set forth in the listing of the claims that begins on page 19 of this paper;

**Remarks** start at page 24 of this paper.